

## AMENDMENTS TO THE CLAIMS

1-6. (Cancelled)

7. (Currently Amended) A method of etching molybdenum on a substrate, comprising:

preparing a solution comprising 5 to 20 % by weight of hydrogen peroxide ( $\text{H}_2\text{O}_2$ ), 75 to 94% by weight of water, and an additive activating an etching action of the hydrogen peroxide [, including a pH controlling agent]; and

applying the solution to etch the molybdenum on the substrate.

8. (Original) The method of claim 7, wherein applying the solution to the substrate comprises spraying the solution onto the substrate.

9. (Original) The method of claim 7, wherein applying the solution to the substrate comprises immersing the substrate into the solution.

10. (Original) The method of claim 7, wherein the solution is applied to the substrate at a temperature of between 20°C to 50°C.

11. (Original) The method of claim 7, wherein the solution is applied to the substrate at a temperature of between 30°C to 45°C.

12. (Previously Presented) The method of claim 7, wherein the additive includes one of sodium dihydrogen citrate/disodium citrate, disodium hydrogen phosphate/trisodium citrate, and ammonium acetate.

13. (Previously Presented) The method of claim 7, wherein the additives include one of surfactants and metal corrosion inhibiting agents.

14. (Previously Presented) The method of claim 7, wherein the water has a resistance greater than about 15 m $\Omega$ /cm.

15. (Previously Presented) The method of claim 7, wherein the solution contains about 8 to 16% by weight of hydrogen peroxide ( $\text{H}_2\text{O}_2$ ).

16. (Previously Presented) The method of claim 7, wherein an etching rate of the solution is about 1000 Å/min.

17. (New) The method of claim 7, wherein the additive include a pH controlling agent.